

# GSM9107

## 30V P-Channel Enhancement Mode MOSFET

### Product Description

GSM9107, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge. These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

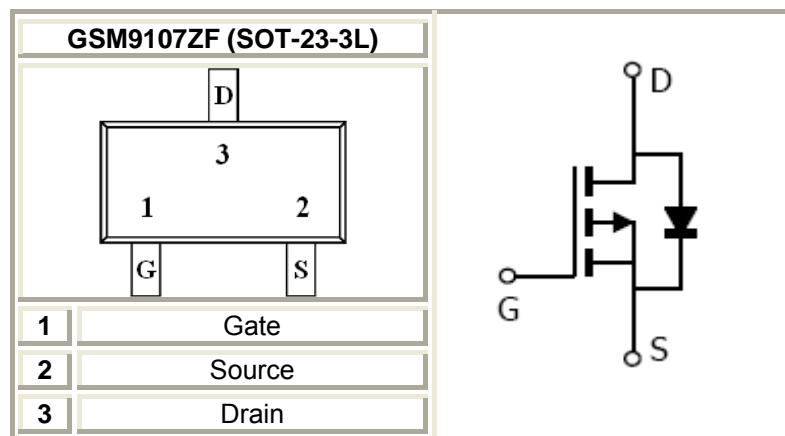
### Features

- -30V/-4.0A,  $R_{DS(ON)}=65m\Omega@V_{GS}=-10.0V$
- -30V/-3.2A,  $R_{DS(ON)}=80m\Omega@V_{GS}=-4.5V$
- -30V/-1.0A,  $R_{DS(ON)}=105m\Omega@V_{GS}=-2.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- SOT-23-3L package design

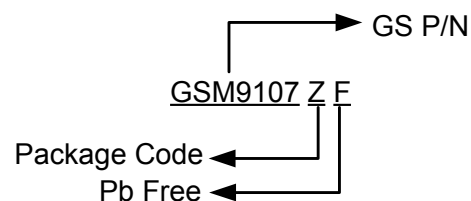
### Applications

- Power Management in Note book
- LED Display
- DC-DC System
- LCD Panel

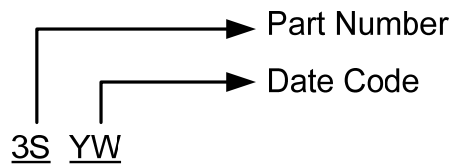
### Packages & Pin Assignments



### Ordering Information



## Marking Information



Part Number	Package	Part Marking
GSM9107ZF	SOT-23-3L	3SYW

## Absolute Maximum Ratings

TA=25°C unless otherwise noted

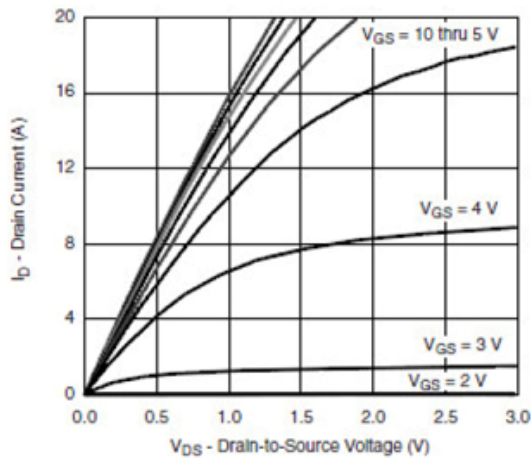
Symbol	Parameter	Typical	Unit	
V <sub>DSS</sub>	Drain-Source Voltage	-30	V	
V <sub>GSS</sub>	Gate –Source Voltage	±12	V	
I <sub>D</sub>	Continuous Drain Current(T <sub>J</sub> =150°C)	TA=25°C	-4.0	A
		TA=70°C	-3.2	
I <sub>DM</sub>	Pulsed Drain Current	-15	A	
I <sub>S</sub>	Continuous Source Current(Diode Conduction)	-1.5	A	
P <sub>D</sub>	Power Dissipation	TA=25°C	1.25	W
		TA=70°C	0.8	
T <sub>J</sub>	Operating Junction Temperature	150	°C	
T <sub>STG</sub>	Storage Temperature Range	-55/150	°C	
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient	120	°C/W	

## Electrical Characteristics

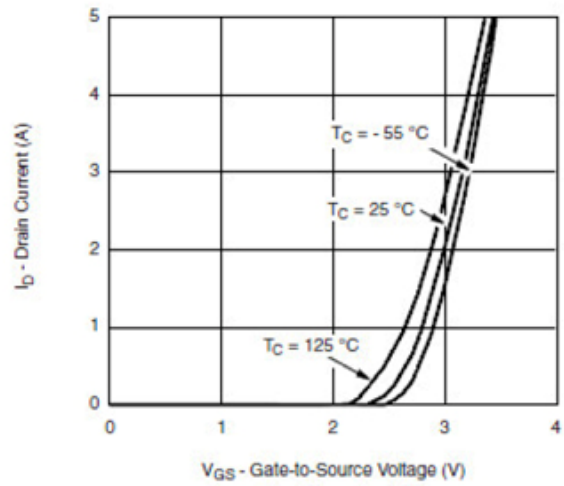
TA=25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
<b>Static</b>							
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30			V	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.6		-1.1		
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 12V$			$\pm 100$	nA	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-24V, V_{GS}=0V$			-1	uA	
		$V_{DS}=-24V, V_{GS}=0V$ $T_A=85^\circ C$			-30		
$I_{D(on)}$	On-State Drain Current	$V_{DS} \leq -5V, V_{GS}=-4.5V$	-6			A	
		$V_{DS} \leq -5V, V_{GS}=-2.5V$	-3				
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-4.0A$		55	65	mΩ	
		$V_{GS}=-4.5V, I_D=-3.2A$		65	80		
		$V_{GS}=-2.5V, I_D=-1.0A$		82	105		
$g_{fs}$	Forward Transconductance	$V_{DS}=-5.0V, I_D=-2.8A$		6.5		S	
$V_{SD}$	Diode Forward Voltage	$I_S=-1.0A, V_{GS}=0V$		-0.7	-1.3	V	
<b>Dynamic</b>							
$Q_g$	Total Gate Charge	$V_{DS}=-15V,$ $V_{GS}=-10V, I_D=-4.0A$		10	18	nC	
$Q_{gs}$	Gate-Source Charge			1.6			
$Q_{gd}$	Gate-Drain Charge			3.0			
$C_{iss}$	Input Capacitance	$V_{DS}=-15V,$ $V_{GS}=0V, f=1MHz$		450		pF	
$C_{oss}$	Output Capacitance			95			
$C_{rss}$	Reverse Transfer Capacitance			55			
$t_{d(on)}$	Turn-On Time	$V_{DD}=-15V,$ $R_L=15\Omega, I_D=-1.0A,$ $V_{GEN}=-10V, R_G=6\Omega$		8	18	ns	
$t_r$				8	18		
$t_{d(off)}$			Turn-Off Time		25		50
$t_f$					25		35

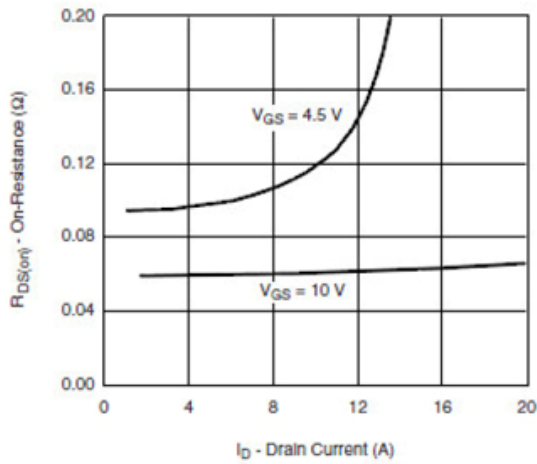
## Typical Performance Characteristics



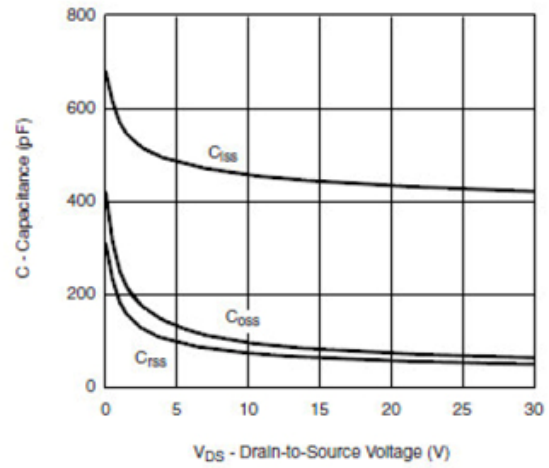
Output Characteristics



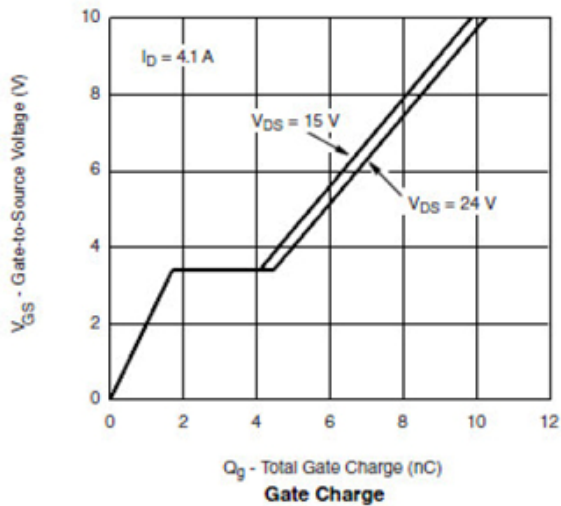
Transfer Characteristics



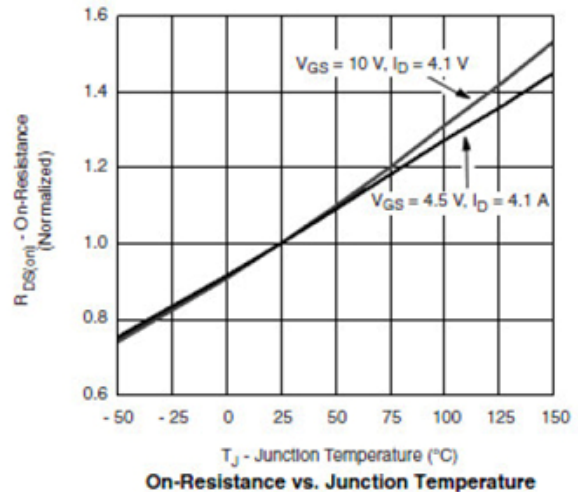
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

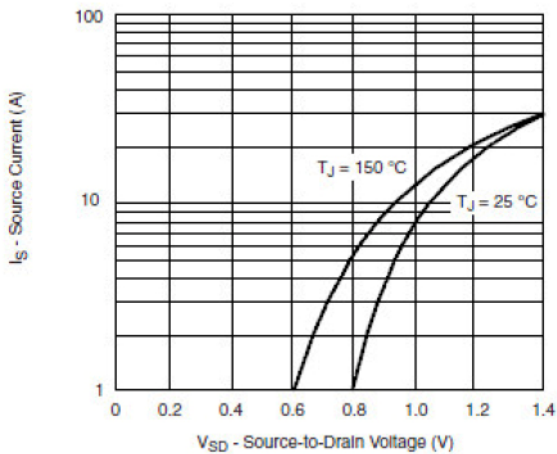


Gate Charge

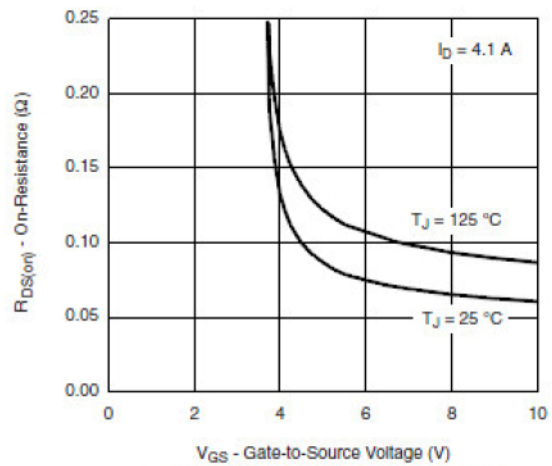


On-Resistance vs. Junction Temperature

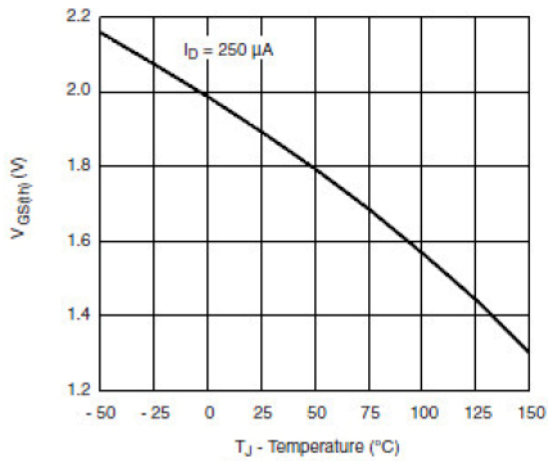
## Typical Performance Characteristics (continue)



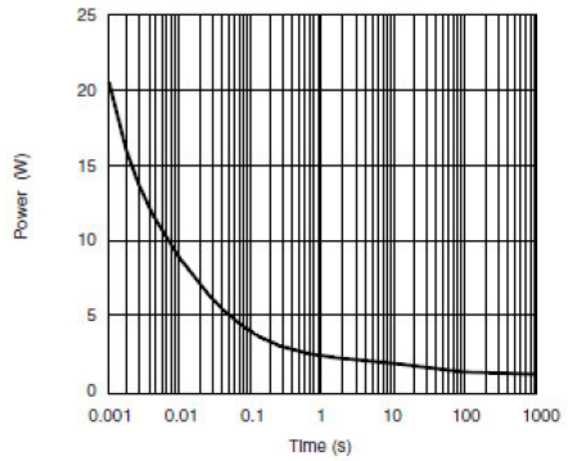
Source-Drain Diode Forward Voltage



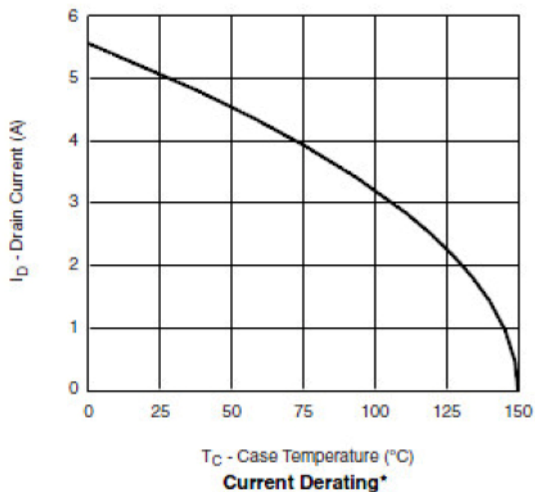
On-Resistance vs. Gate-to-Source Voltage



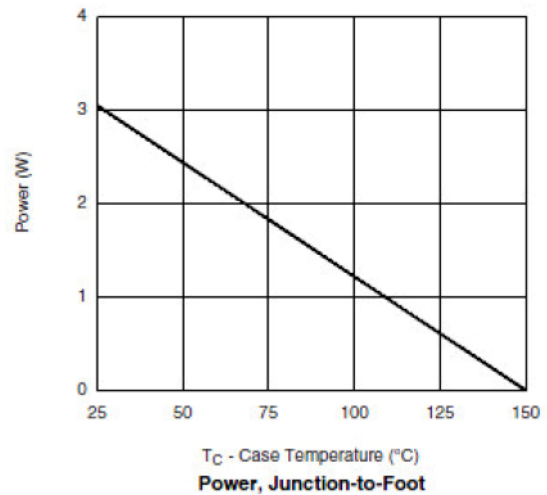
Threshold Voltage



Single Pulse Power

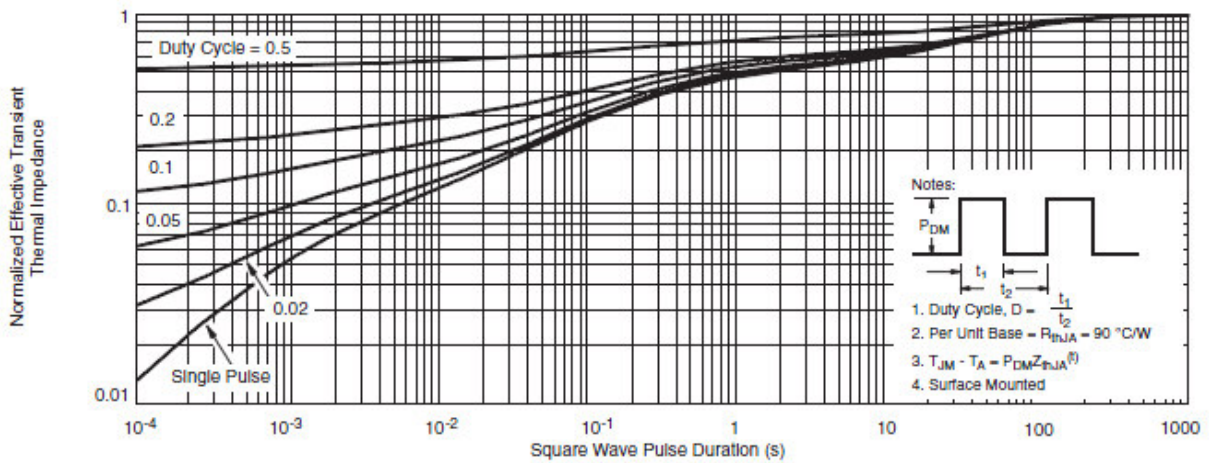


Current Derating\*

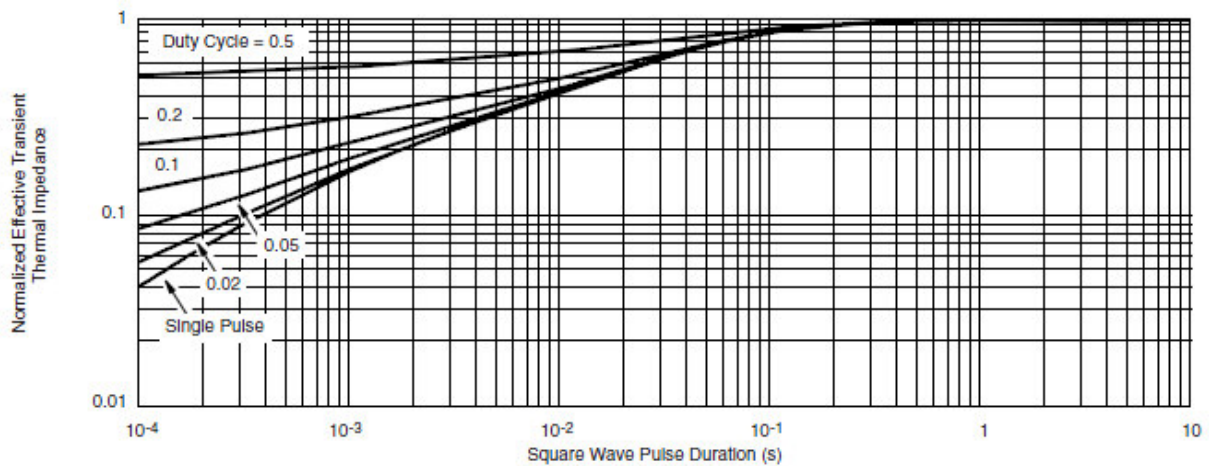


Power, Junction-to-Foot

## Typical Characteristics



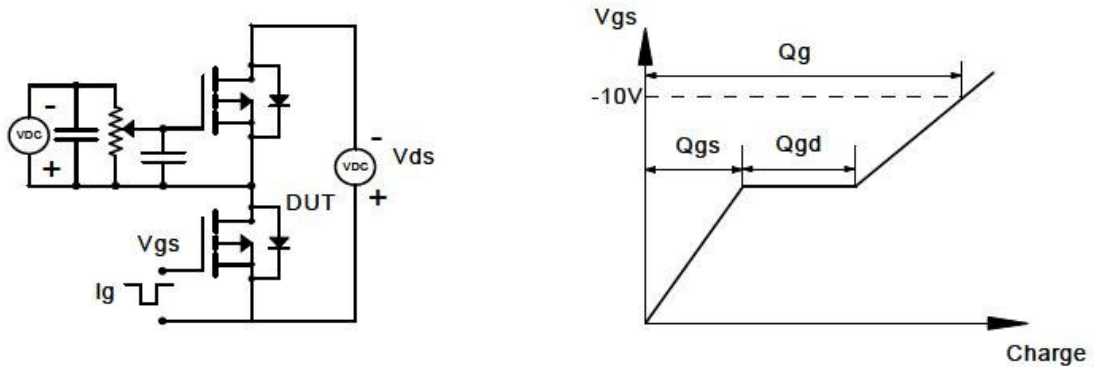
Normalized Thermal Transient Impedance, Junction-to-Ambient



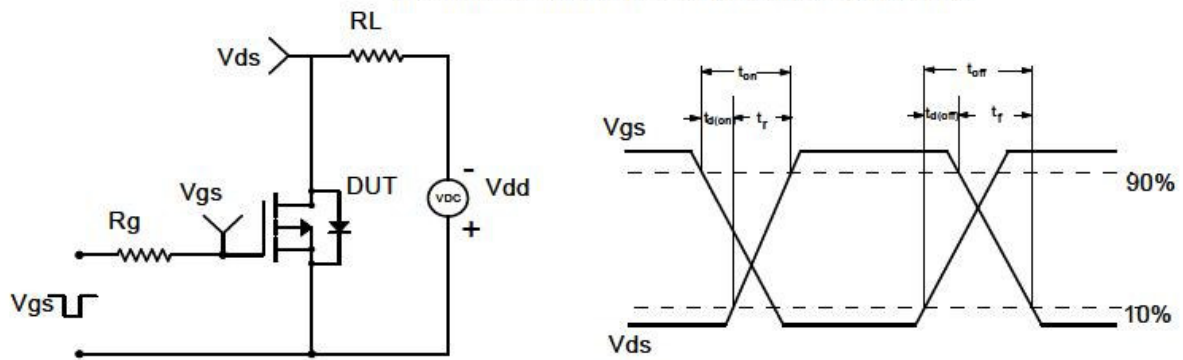
Normalized Thermal Transient Impedance, Junction-to-Foot

## Typical Characteristics (continue)

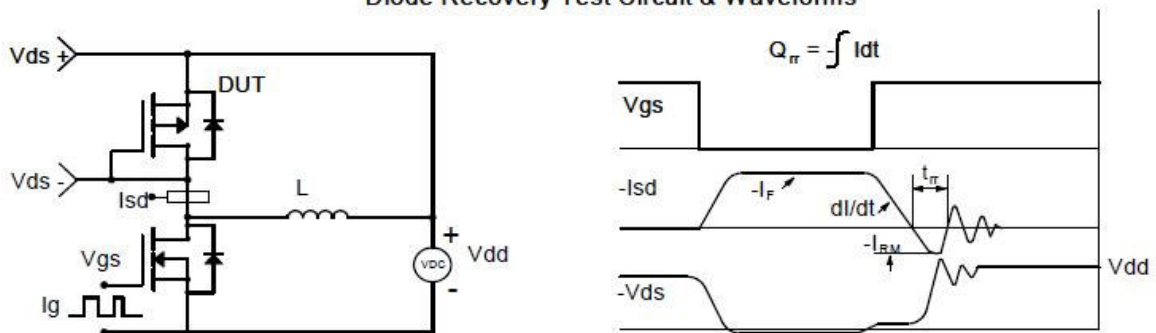
### Gate Charge Test Circuit & Waveform



### Resistive Switching Test Circuit & Waveforms

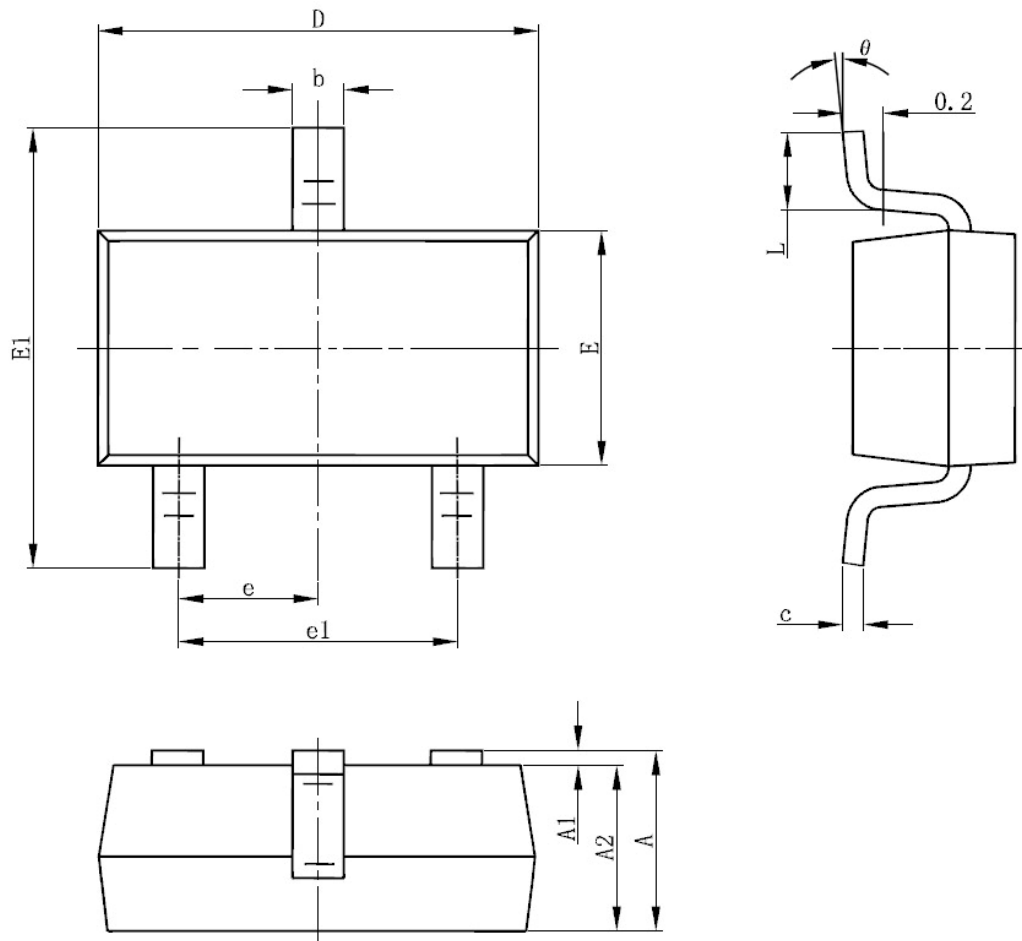


### Diode Recovery Test Circuit & Waveforms



## Package Dimension

### SOT-23-3L



### Dimensions





SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	1.05	1.25	0.041	0.049
A1	0	0.1	0	0.004
A2	1.05	1.15	0.041	0.045
b	0.3	0.5	0.012	0.020
c	0.1	0.2	0.004	0.008
D	2.82	3.02	0.111	0.119
E	1.5	1.7	0.059	0.067
E1	2.65	2.95	0.104	0.116
e	0.950 (TYP)		0.037 (TYP)	
e1	1.8	2	0.071	0.079
L	0.3	0.6	0.012	0.024
Q	0°	8°	0°	8°





## NOTICE

Information furnished is believed to be accurate and reliable. However Globaltech Semiconductor assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties, which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Globaltech Semiconductor. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information without express written approval of Globaltech Semiconductor.

## CONTACT US

GS Headquarter	
	4F.,No.43-1,Lane11,Sec.6,Minquan E.Rd NeiHu District Taipei City 114, Taiwan (R.O.C)
	886-2-2657-9980
	886-2-2657-3630
	sales_twn@gs-power.com

Wu-Xi Branch	
	No.21 Changjiang Rd., WND, Wuxi, Jiangsu, China (INFO. & TECH. Science Park Building A 210 Room)
	86-510-85217051
	86-510-85211238
	sales_cn@gs-power.com

RD Division	
	824 Bolton Drive Milpitas. CA. 95035
	1-408-457-0587

[www.s-manuals.com](http://www.s-manuals.com)